



# Product Change Notification

**Change Notification #:** PCN114773 - 00  
**Change Title:** Intel® Server System R1304WTTGSR,  
Intel® Server System R2224WTTYSR,  
Intel® Server System R1208WTTGSR,  
PCN114773 – 00, Product Design,  
DIMM connector change  
**Date of Publication:** July 14, 2016

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	August 1, 2016
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## Description of Change to the Customer:

Intel is implementing the following change on the Intel® Server Systems R1304WTTGSR, R2224WTTYSR and R1208WTTGSR:

- Replaced DIMM connector to increase gold plating thickness from 15u” to 30u” for higher durability

## Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

## Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre TA#	Post TA#	Pre-PBA	Post-PBA
R1304WTTGSR	943891	J11482-002	J11482-003	G92187-366	G92187-367
R2224WTTYSR	943831	J11492-003	J11492-004	G92187-366	G92187-367
R1208WTTGSR	943893	J11481-002	J11481-003	G92187-366	G92187-367

## PCN Revision History:

<b>Date of Revision:</b> July 14, 2016	<b>Revision Number:</b> 00	<b>Reason:</b> Originally Published PCN
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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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